## 09/872.713

- 1-10. (CANCELED)
- 11. (PREVIOUSLY PRESENTED) The thermal conductive material according to claim 19, wherein the thermal conductive material is plasticized at 60°C under a pressure equal to or above 6.0 g/cm<sup>2</sup>.
  - 12. (CANCELED)
- 13. (PREVIOUSLY PRESENTED) The thermal conductive material according to claim 19, wherein the thermal conductive material is in an elastomeric state at room temperature.
- 14. (PREVIOUSLY PRESENTED) The thermal conductive material according to claim 19, wherein the organic material is an olefin resin.
  - 15. (CANCELED)
- 16. (PREVIOUSLY PRESENTED) The thermal conductive material according to claim 19, wherein the filler is at least one of ceramics, metallic powder, metallic magnetic body and carbon fiber.
- 17. (PREVIOUSLY PRESENTED) The thermal conductive material according to claim 19, wherein the filler is a material serving as an electromagnetic shield.
  - 18. (CANCELED)
  - 19. (CURRENTLY AMENDED) A thermal conductive material comprising:
- an unvulcanized ethylene-propylene-diene terpolymer, EPDM organic material; and
- a filler having a higher thermal conductivity than the unvulcanized EPDM < ethylene-propylene-diene terpolymer organic material,
  - wherein the thermal conductive material is plasticized at a temperature in the range of 30-65°C and the thermal conductive material changes form to flexibly correspond to a form of a surface of a member with which the thermal conductive
- < material comes in contact; and
- the unvulcanized ethylene-propylene-diene terpolymer organic material has
- < a melting transition in the range of 30-70°C and a viscosity at 100°C is equal to or
- < above 70,000cP, a weight ratio of the filler to the thermal conductive material is in the
- < range of 30-90 weight %.